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Growth inhibition of interfacial intermetallic compounds by pre-coating oriented Cu_6Sn_5 grains on Cu substrates

Ming Yang, Yong-Ho Ko, Jung-Hwan Bang, Taek-Soo Kim, Chang-Woo Lee, Shuye Zhang, Mingyu Li

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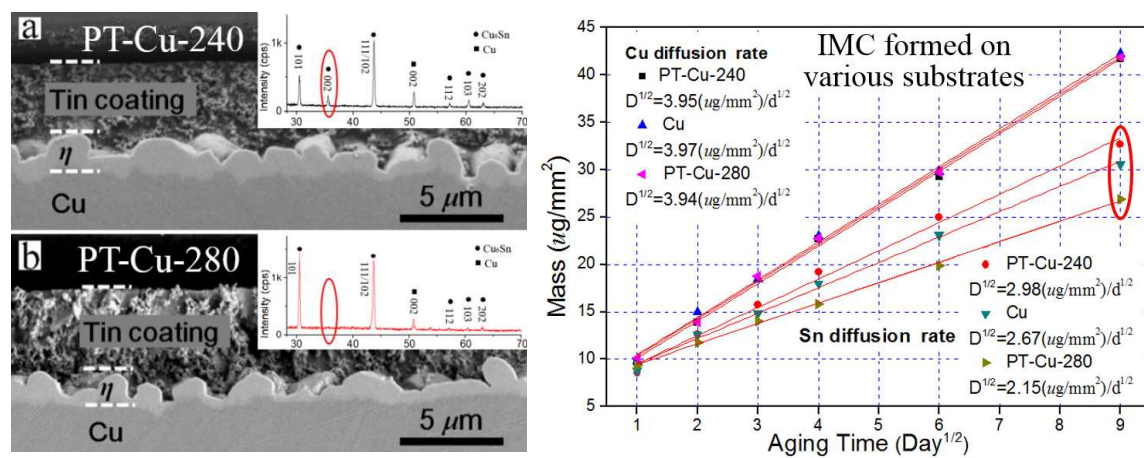
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